

FIG. 1 PRIOR ART

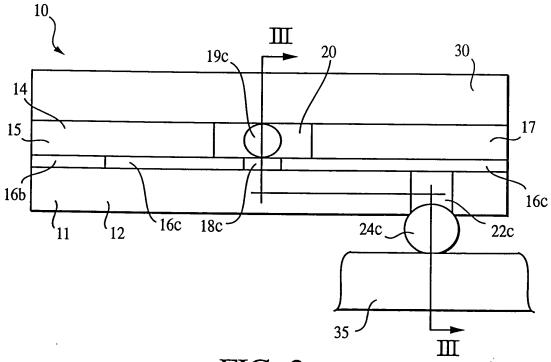


FIG. 2 PRIOR ART

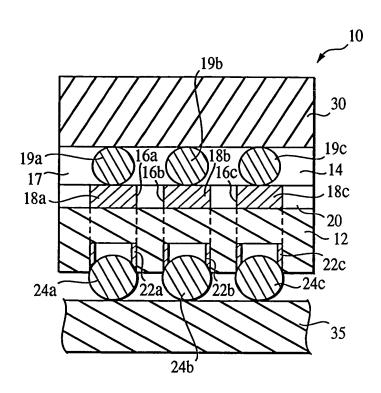


FIG. 3 PRIOR ART

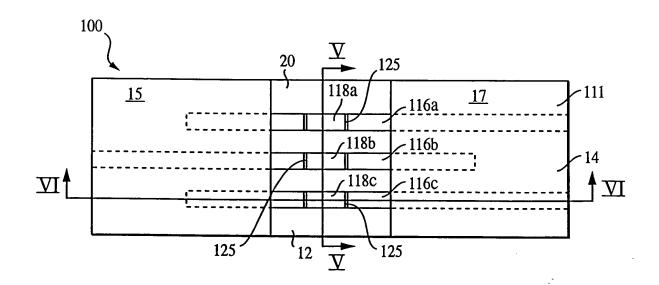


FIG. 4

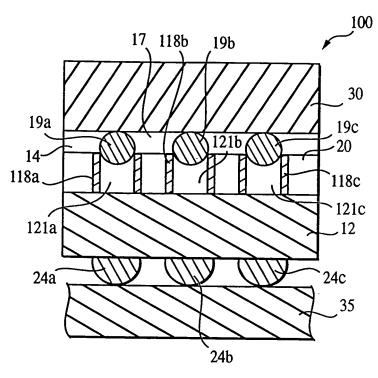
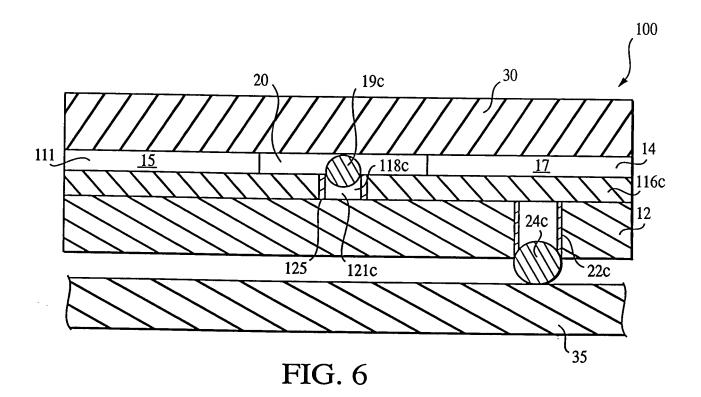
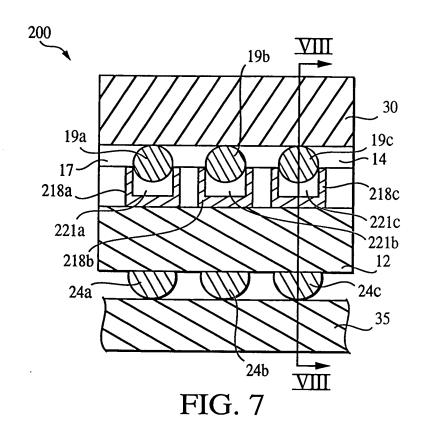
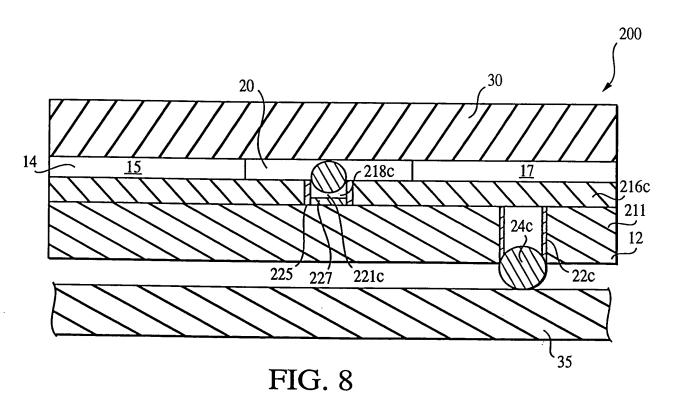
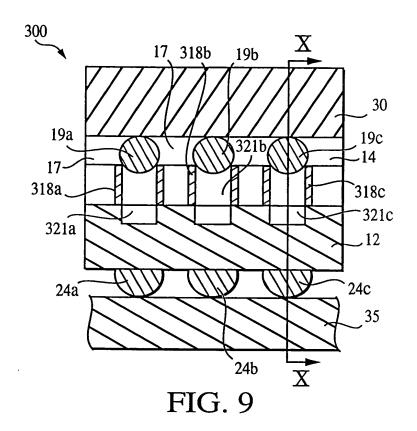


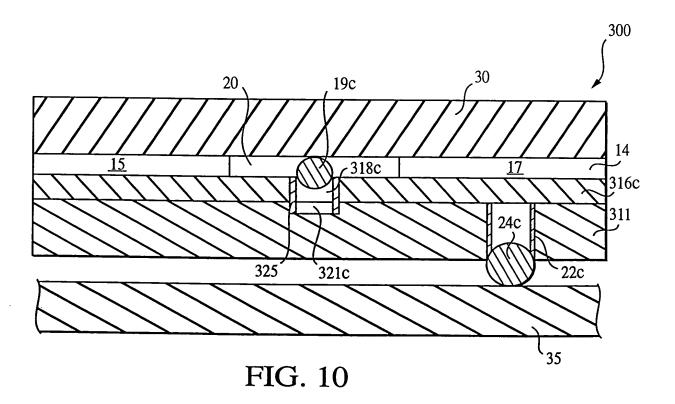
FIG. 5











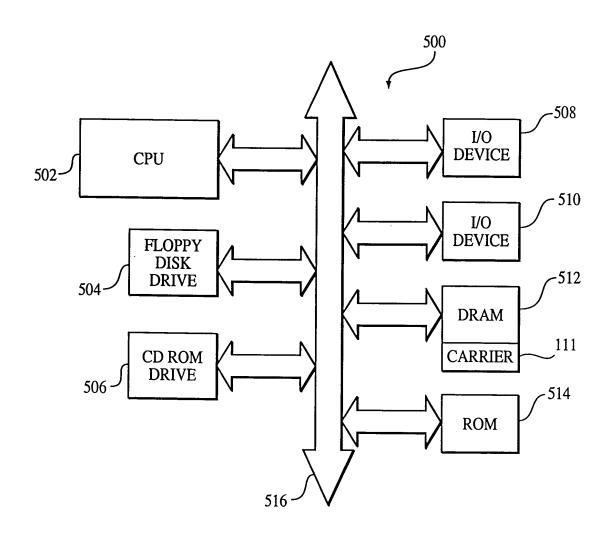


FIG. 11

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Title: _NTER BOND FLIP CHIP SEMICONDUCTO: CARRIER AND A METHOD OF MAKING AND USING IT

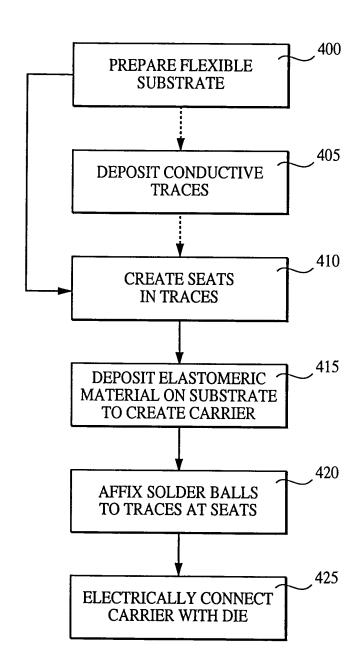


FIG. 12

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Title: __NTER BOND FLIP CHIP SEMICONDUCTO:
CARRIER AND A METHOD OF MAKING AND USING IT

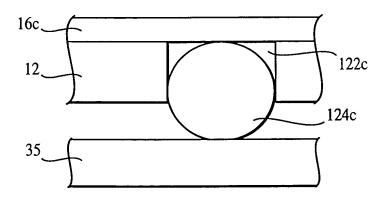


FIG. 13

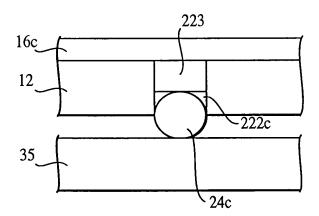


FIG. 14